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Texas Instruments Enhanced Products Reliability Report

(Subject To Attached Disclaimers)

Device Type/Device Family: UC2832TDWEP
 Package Type: 16 SOIC
 Wafer Fabrication Facility: Ti Sherman Facility
 Assembly/Test Facility: Carsem
 Compiledd: 02/13

Biased Life Test

Test Method: JESD22-A108
 Test Condition: 150°/500 hours or Equiv
 Sample Size: 8133
 Rejects: 0
 Activation Energy (eV): .5
 Equivalent Device Hours: 26.17E6
 Failure Rate (FIT)*: 35.2

*Derated to +55°C with a 60% Confidence Level

Note: Data for EP product is specific to device technology and foundry. For this reason the FIT rate above may differ from Ti’s external web page. This does not reflect a difference in quality but only a difference in sample size.

Package Related Tests

<u>Description</u>	<u>Condition</u>	<u>Referenced Method</u>	<u>Sample Size/Rejects</u>	
Biased Humidity or HAST	130°C / 85% / 250 hours**	JESD22-A101 JESD22-A110	231/0	*
Autoclave	121 °C @ 2 atmospheres absolute for 96 hours	JESD22-A102	231/0	*
Temperature Cycle	-65 °C to +150 °C non-biased for 1000 cycles	JESD22-A104	231/0	*
High Temp Storage	170 °C / 420 hours	JESD22-A103-A	231/0	*

* Preconditioning per JEDEC Std. 22, Method A112/A113

** This device has been qualified to the elevated standard of 250 Hrs 130/85 HAST (Highly Accelerated Stress Test). This qualification level surpasses JEDEC requirements.

Initial Product Qualification

The subject Enhanced Plastic device, device family, and/or package family have passed Texas Instruments product qualification as follows:

<u>Description</u>	<u>Condition</u>	<u>Sample Size</u>	<u>Referenced Method</u>	
Electrical Characterization	TI Data Sheet	50 units/lot	N/A	
Electrostatic Discharge Sensitivity	HBM MM	3 units/voltage	EIA/JESD22-A114 EIA/JESD22-A115	
Latch-up	Per Technology	5/0 units/lot	EIA/JESD78	
Physical Dimensions	TI Data Sheet	5/0	EIA/JESD22- B100	
Thermal Impedance	Theta-JA on board	Per Pin-Package	EIA/JESD51	
Bias Life Test	125°C / 1000 hours or equivalent	116/0	JESD22-A108	*
Biased Humidity	85°C / 85% / 1000 hours or HAST	77/0	JESD22-A101	*
	130°C / 85% / 96 hours		JESD22-A110	
Autoclave	121 °C @ 2 atmospheres absolute for 96 hours	77/0	JESD22-A102	*
Temperature Cycle	-65 °C to +150 °C non-biased for 1,000 cycles	77/0	JESD22-A104	*
Solder Heat	260 °C for 10 seconds	22/0	JESD22-B106	
Resistance to Solvents	Ink symbol only	12/0	JESD22-B107	
Solderability	Condition A (steam age for 8 hours)	22/0	ANSI/J-STD-002-92	
Flammability	Method A / Method B	5/0	UL-1964	
Bond Strength	-	76/0 wires	ASTM F-459	
Die Shear	-	5/0	MIL-STD-883 Method 2019	
High Temp Storage	150 °C / 1,000 hours	45/0	JESD22-A103-A	*
Moisture Sensitivity	Surface Mount Only	12/0	J-STD-020-A	

* Precondition performed

Supplemental Device Characteristics

Die Revision:	-	Assembly Site:	Carsem
Master Die:	SMFXC2832IS	Package Type:	DW
Wafer Fab:	Ti Sherman	Pin Count:	16
Fab Technology:	BiPolar	Mold Compound:	Sumitomo EME-G600C
Fab Process:	BiPolar	Mount Compound:	Ablestik 8290
Process Code:	N/A	Bond:	1.3 Mil Au
Passivation:	Nitride	Lead Composition:	Cu
Metal 1:	AlCu2	Lead Finish:	NiPdAu
Metal 2:	N/A	Die Size:	130 X 157 Mils

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